





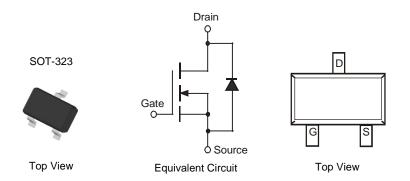
N-CHANNEL ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT-323
- Case Material: Molded Plastic, "Green" Molding Compound, Note 6. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Weight: 0.006 grams (approximate)



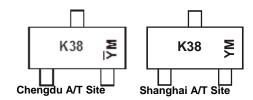
Ordering Information (Note 4)

| Part Number | Case | Packaging |
|--------------|---------|------------------|
| BSS138W -7-F | SOT-323 | 3000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

Marking Information



 $\begin{array}{l} K38 = Product\ Type\ Marking\ Code \\ YM = Date\ Code\ Marking\ for\ SAT\ (Shanghai\ Assembly/\ Test\ site) \\ \overline{Y}M = Date\ Code\ Marking\ for\ CAT\ (Chengdu\ Assembly/\ Test\ site) \\ Y\ or\ \overline{Y} = Year\ (ex:\ A=2013) \\ M = Month\ (ex:\ 9=September) \end{array}$

Date Code Key

| Year | 201 | 2 | 2013 | | 2014 | 20 | 15 | 2016 | | 2017 | 1 | 2018 |
|-------|-----|-----|------|-----|------|-----|-----|------|-----|------|-----|------|
| Code | Z | | Α | | В | (| | D | | Е | | F |
| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 0 | N | D |



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

| Characteristic | Symbol | Value | Units | |
|-----------------------------|------------|------------------|-------|----|
| Drain-Source Voltage | | V _{DSS} | 50 | V |
| Drain-Gate Voltage (Note 5) | | V_{DGR} | 50 | V |
| Gate-Source Voltage | Continuous | V _{GSS} | ±20 | V |
| Drain Current (Note 6) | Continuous | I _D | 200 | mA |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Units |
|---|-----------------|-------------|-------|
| Total Power Dissipation (Note 6) | P_{D} | 200 | mW |
| Thermal Resistance, Junction to Ambient | $R_{\theta JA}$ | 625 | °C/W |
| Operating and Storage Temperature Range | T_J, T_{STG} | -55 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|-----------------------------------|----------------------|-----|-----|------|------|--|--|
| OFF CHARACTERISTICS (Note 7) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 50 | 75 | _ | V | $V_{GS} = 0V, I_D = 250\mu A$ | |
| Zero Gate Voltage Drain Current | I _{DSS} | | | 0.5 | μΑ | $V_{DS} = 50V$, $V_{GS} = 0V$ | |
| Gate-Body Leakage | I _{GSS} | | | ±100 | nA | $V_{GS} = \pm 20V, V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 7) | | | | a | | _ | |
| Gate Threshold Voltage | V _{GS(th)} | 0.5 | 1.2 | 1.5 | > | $V_{DS} = V_{GS}$, $I_D = 250\mu A$ | |
| Static Drain-Source On-Resistance | R _{DS (ON)} | | 1.4 | 3.5 | Ω | $V_{GS} = 10V, I_D = 0.22A$ | |
| Forward Transconductance | g _{FS} | 100 | | | mS | $V_{DS} = 25V$, $I_D = 0.2A$, $f = 1.0KHz$ | |
| DYNAMIC CHARACTERISTICS (Note 8) | | | | | | | |
| Input Capacitance | Ciss | _ | _ | 50 | pF | | |
| Output Capacitance | Coss | | | 25 | рF | $V_{DS} = 10V, V_{GS} = 0V, f = 1.0MHz$ | |
| Reverse Transfer Capacitance | C _{rss} | | | 8.0 | pF | 1 | |
| SWITCHING CHARACTERISTICS(Note 8) | | | | | | | |
| Turn-On Delay Time | t _{D(ON)} | | | 20 | ns | $V_{DD} = 30V, I_D = 0.2A,$ | |
| Turn-Off Delay Time | t _{D(OFF)} | _ | _ | 20 | ns | $R_{GEN} = 50\Omega$ | |

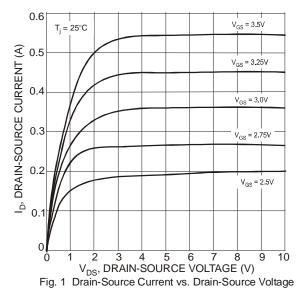
Notes: 5. $R_{GS} \le 20 K\Omega$.

6. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com.

^{7.} Short duration pulse test used to minimize self-heating effect.

^{8.} Guaranteed by design. Not subject to production testing.







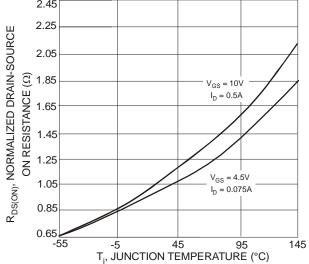


Fig. 3 Drain-Source On Resistance vs. Junction Temperature

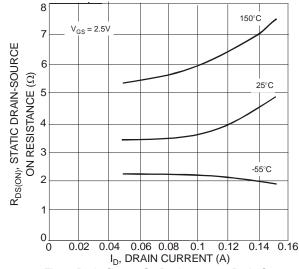
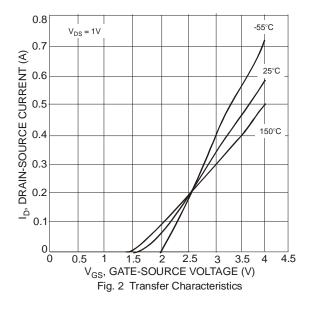


Fig. 5 Drain-Source On Resistance vs. Drain Current



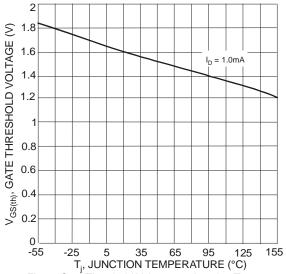


Fig. 4 Gate Threshold Voltage vs. Junction Temperature

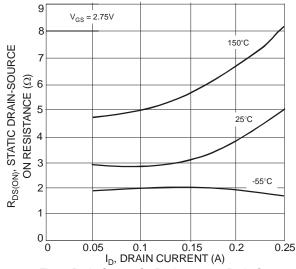
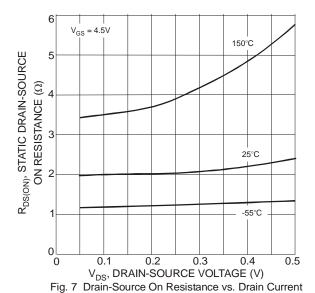
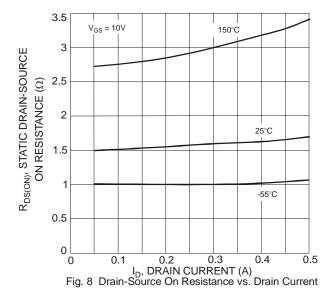
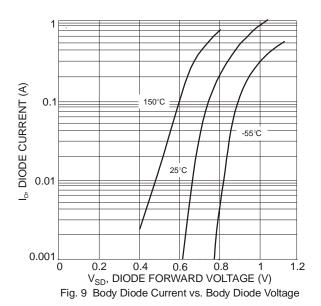


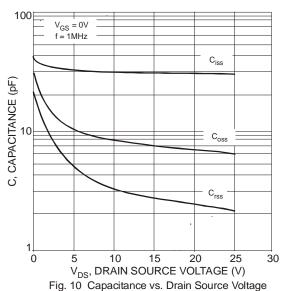
Fig. 6 Drain-Source On Resistance vs. Drain Current



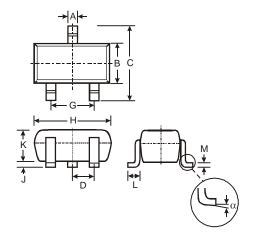








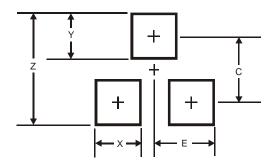
Package Outline Dimensions



| SOT-323 | | | | | | | |
|---------|----------------------|------|------|--|--|--|--|
| Dim | Min | Max | Тур | | | | |
| Α | 0.25 | 0.40 | 0.30 | | | | |
| В | 1.15 | 1.35 | 1.30 | | | | |
| С | 2.00 | 2.20 | 2.10 | | | | |
| D | - | - | 0.65 | | | | |
| G | 1.20 | 1.40 | 1.30 | | | | |
| Н | 1.80 | 2.20 | 2.15 | | | | |
| J | 0.0 | 0.10 | 0.05 | | | | |
| K | 0.90 | 1.00 | 0.95 | | | | |
| L | 0.25 | 0.40 | 0.30 | | | | |
| M | 0.10 | 0.18 | 0.11 | | | | |
| α | 0° | 8° | - | | | | |
| All | All Dimensions in mm | | | | | | |



Suggested Pad Layout



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 2.8 |
| Х | 0.7 |
| Υ | 0.9 |
| С | 1.9 |
| E | 1.0 |

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